## 100V PNP LOW SATURATION MEDIUM POWER TRANSISTOR IN SOT89

### SUMMARY

 $\text{BV}_{\text{CEO}}$  = -100V :  $\text{R}_{\text{SAT}}$  = 57m $\Omega$ ;  $\text{I}_{\text{C}}$  = -3.5A

#### DESCRIPTION

Packaged in the SOT89 outline this new low saturation 100V PNP transistor offers low on state losses making it ideal for use in DC-DC circuits, line switching and various driving and power management functions.

### FEATURES

- 3.5 amps continuous current
- Up to 10 amps peak current
- Very low saturation voltages

### **APPLICATIONS**

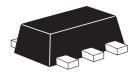
- Motor driving
- Line switching
- High side switches
- Subscriber line interface cards (SLIC)

### **ORDERING INFORMATION**

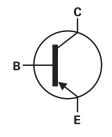
DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXTP2013ZTA	7"	12mm embossed	1,000 units

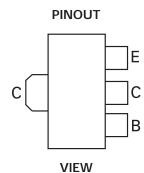
## DEVICE MARKING

953



**SOT89** 





## ABSOLUTE MAXIMUM RATINGS

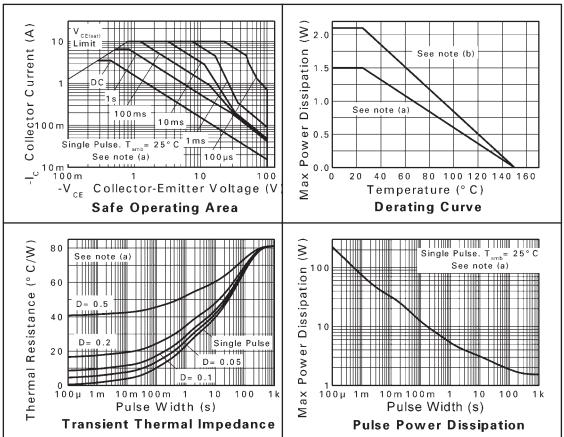
PARAMETER	SYMBOL	LIMIT	UNIT
Collector-base voltage	BV <sub>CBO</sub>	-140	V
Collector-emitter voltage	BV <sub>CEO</sub>	-100	V
Emitter-base voltage	BV <sub>EBO</sub>	-7	V
Continuous collector current <sup>(a)</sup>	I <sub>C</sub>	-3.5	А
Peak pulse current	I <sub>CM</sub>	-10	А
Power dissipation at T <sub>A</sub> =25°C <sup>(a)</sup>	P <sub>D</sub>	1.5	W
Linear derating factor		12	mW/°C
Power dissipation at T <sub>A</sub> =25°C <sup>(b)</sup>	P <sub>D</sub>	2.1	W
Linear derating factor		16.8	mW/°C
Operating and storage temperature range	T <sub>j</sub> , T <sub>stg</sub>	-55 to 150	°C

### THERMAL RESISTANCE

PARAMETER	SYMBOL	LIMIT	UNIT
Junction to ambient <sup>(a)</sup>	$R_{\theta JA}$	83	°C/W
Junction to ambient <sup>(b)</sup>	$R_{\theta JA}$	60	°C/W

NOTES:

(a) For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
(b) For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

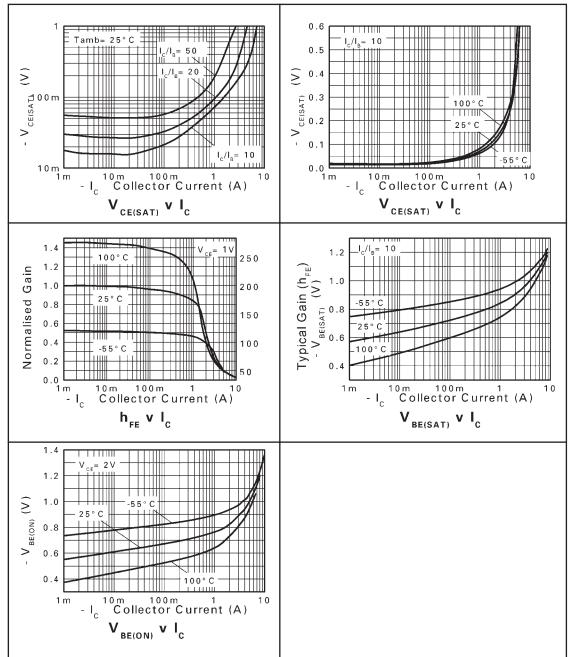


CHARACTERISTICS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Collector-base breakdown voltage	BV <sub>CBO</sub>	-140	-160		V	I <sub>C</sub> = -100μA
Collector-emitter breakdown voltage	BV <sub>CER</sub>	-140	-160		V	$I_{C}$ = -1µA, RB $\leq$ 1k $\Omega$
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	-100	-115		V	I <sub>C</sub> = -10mA*
Emitter-base breakdown voltage	BV <sub>EBO</sub>	-7	-8.1		V	I <sub>E</sub> = -100μA
Collector cut-off current	I <sub>CBO</sub>		<1	-20	nA	V <sub>CB</sub> = -100V
				-0.5	μA	$V_{CB} = -100V, T_{amb} = 100^{\circ}C$
Collector cut-off current	I <sub>CER</sub>		<1	-20	nA	V <sub>CB</sub> = -100V
	$R \leq 1k\Omega$			-0.5	μA	$V_{CB} = -100V, T_{amb} = 100^{\circ}C$
Emitter cut-off current	I <sub>EBO</sub>		<1	-10	nA	$V_{EB} = -6V$
Collector-emitter saturation voltage	V <sub>CE(SAT)</sub>		-20	-30	mV	I <sub>C</sub> = -0.1A, I <sub>B</sub> = -10mA*
			-65	-85	mV	I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA*
			-110	-135	mV	$I_{C} = -2A, I_{B} = -200 \text{mA}^{*}$
			-230	-300	mV	$I_{C} = -4A, I_{B} = -400 \text{mA}^{*}$
Base-emitter saturation voltage	V <sub>BE(SAT)</sub>		-970	-1060	mV	$I_{C} = -4A$ , $I_{B} = -400 \text{mA}^{*}$
Base-emitter turn on voltage	V <sub>BE(ON)</sub>		-910	-1030	mV	$I_{C} = -4A, V_{CE} = -1V^{*}$
Static forward current transfer ratio	h <sub>FE</sub>	100	250			$I_{C} = -10mA$ , $V_{CE} = -1V^{*}$
		100	200	300		$I_{C} = -1A, V_{CE} = -1V^{*}$
		25	50			$I_{C} = -3A, V_{CE} = -1V^{*}$
		15	30			$I_{C} = -4A, V_{CE} = -1V^{*}$
			5			$I_{C} = -10A, V_{CE} = -1V^{*}$
Transition frequency	f <sub>T</sub>		125		MHz	I <sub>C</sub> = 100mA, V <sub>CE</sub> = 10V
						f=50MHz
Output capacitance	C <sub>OBO</sub>		42		рF	V <sub>CB</sub> = -10V, f= 1MHz*
Switching times	t <sub>ON</sub>		42		ns	$I_{\rm C} = 1 {\rm A}, {\rm V}_{\rm CC} = 10 {\rm V},$
	t <sub>OFF</sub>		540			I <sub>B1</sub> = I <sub>B2</sub> = 100mA

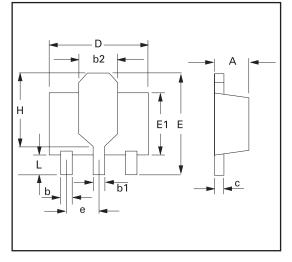
# **ELECTRICAL CHARACTERISTICS** (at $T_{amb} = 25^{\circ}C$ unless otherwise stated)

\* Measured under pulsed conditions. Pulse width  $\leq 300 \mu s;$  duty cycle  $\leq 2\%.$ 



#### **TYPICAL CHARACTERISTICS**

### PACKAGE OUTLINE



#### PACKAGE DIMENSIONS

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
DIIVI	Min	Max	Min	Max	DIIVI	Min	Max	Min	Max
А	1.40	1.60	0.550	0.630	е	1.40	1.50	0.055	0.059
b	0.38	0.48	0.015	0.019	E	3.75	4.25	0.150	0.167
b1	-	0.53	-	0.021	E1	-	2.60	-	0.102
b2	1.50	1.80	0.060	0.071	G	2.90	3.00	0.114	0.118
с	0.28	0.44	0.011	0.017	н	2.60	2.85	0.102	0.112
D	4.40	4.60	0.173	0.181	-	-	-	-	-

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